

# Z-PACK | Z-PACK Future Bus+

TE Internal #: 5536600-1

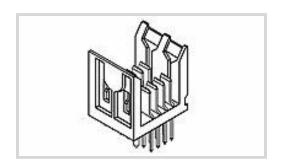
Rectangular Power Connectors, Header, Plug, Board-to-Board, 8 Position, 2 mm [.079 in] Centerline, Printed Circuit Board, UL 94V-0,

Z-PACK Future Bus+

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Connectors > Power Connectors > Rectangular Power > Rectangular Power Connectors



Rectangular Power Connector Type: Header

Connector & Housing Type: Plug
Connector System: Board-to-Board

Number of Positions: 8

Centerline (Pitch): 2 mm [ .079 in ]

# **Features**

# **Product Type Features**

Header Type	Partially Shrouded
Rectangular Power Connector Type	Header
Connector & Housing Type	Plug
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

# **Configuration Features**

Number of Positions	8
Interface Type	Futurebus+
PCB Mount Orientation	Vertical
Number of Power Positions	8
Number of Signal Positions	0
Number of Rows	4

#### **Electrical Characteristics**

Operating Voltage	30 VDC	
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#### **Contact Features**

Contact Layout	Matrix
Contact Base Material	Phosphor Bronze



Contact Current Rating (Max)	3 A, 5 A
Contact Retention Within Housing	With
Contact Type	Pin
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Contact Termination Area Plating Thickness	3.81 – 8.89 μm[150 – 350 μin]
Termination Features	
Termination Post & Tail Length	3.43 mm[.135 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit, Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarizing Rib
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2 mm[.079 in]
Housing Color	Natural
Housing Color Housing Material	Natural  LCP (Liquid Crystal Polymer)
Housing Material	
Housing Material  Dimensions	LCP (Liquid Crystal Polymer)
Housing Material  Dimensions  Row-to-Row Spacing	LCP (Liquid Crystal Polymer)  2 mm[.079 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]  1.6 mm[.063 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)  Height	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]  1.6 mm[.063 in]  17 mm[.668 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)  Height  Width	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]  1.6 mm[.063 in]  17 mm[.668 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)  Height  Width  Usage Conditions	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]  1.6 mm[.063 in]  17 mm[.668 in]  16 mm[.622 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)  Height  Width  Usage Conditions  Operating Temperature Range	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]  1.6 mm[.063 in]  17 mm[.668 in]  16 mm[.622 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)  Height  Width  Usage Conditions  Operating Temperature Range  Operation/Application	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]  1.6 mm[.063 in]  17 mm[.668 in]  16 mm[.622 in]
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)  Height  Width  Usage Conditions  Operating Temperature Range  Operation/Application  Solder Process Feature	LCP (Liquid Crystal Polymer)  2 mm[.079 in]  6.5 mm[.256 in]  1.6 mm[.063 in]  17 mm[.668 in]  16 mm[.622 in]  Board Standoff
Housing Material  Dimensions  Row-to-Row Spacing  Mating Post Length  PCB Thickness (Recommended)  Height  Width  Usage Conditions  Operating Temperature Range  Operation/Application  Solder Process Feature  Circuit Application	2 mm[.079 in] 6.5 mm[.256 in] 1.6 mm[.063 in] 17 mm[.668 in] 16 mm[.622 in]  Board Standoff



### **Packaging Features**

Packaging Method	Tube
Packaging Quantity	48

#### Other

For Use With	Receptacle Assembly

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Pin-in-Paste capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts











# Also in the Series | Z-PACK Future Bus+







Hard Metric Backplane Connectors(1)



Rectangular Power Connectors(35)

### **Documents**

# **Product Drawings**

2MMFB,ASY,008,PWR,HDR,SL,4.25

English

#### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_5536600-1\_O.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_5536600-1\_O.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_5536600-1\_O.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

# Datasheets & Catalog Pages

POWER\_CONNECTORS\_CATALOG\_SEC01\_BOARD\_TO\_BOARD

English

# **Product Specifications**

**Application Specification** 

English

Rectangular Power Connectors, Header, Plug, Board-to-Board, 8 Position, 2 mm [.079 in] Centerline, Printed Circuit Board, UL 94V-0, Z-PACK Future Bus+

